

PART I:

PCBA Capability:

PCB Assembly includes the manufacturing process of Surface Mount Technology(SMT), Manual Insertion (MI), Auto-insertion (AI) and Chip on Board(COB).

- ※ **Surface Mount Technology**
- ※ **Pin Through-hole Assembly**
- ※ **RoHS**
- ※ **Selective Wave Soldering**
- ※ **Conformal Coating**
- ※ **Complete box build**
- ※ **Inspection Methods**

Surface Mount Technology

Employing state of the art DEK printers, Placement machines and BTU convection air reflow ovens. With many years experience of placing BGA, UBGGA, CSP and small profile passives down to and including 0201, the plant offers a cost effective high yield solution to any SMT requirement.

Pin Through Hole

Capabilities to place tape and reeled radial components sizes. Maximum PCB size is 25" x 25". Placement rates reach 5000 pieces per hour with an accuracy of 99% minimizing component loss.

RoHS Regulations

Full lead based processing for exempt category product, whilst also having invested in lead-free equipment and process control.

Selective Wave Solder

Having the Selective Wave soldering machines, with consistent quality and process control when assembling boards having multiple ground and power planes, high-current connectors or A-typical distribution of components.

Conformal coating

Both dip-coating and vertical spray coating is available. Protecting non conductive dielectric layer that is applied onto the printed circuit board assembly to protect the electronic assembly from damage due to contamination, salt spray, moisture, fungus, dust and corrosion caused by harsh or extreme environments. When coated, it is clearly visible as a clear and shiny material.

Complete box build

Complete 'Box Build' solutions including materials management of all components, electromechanical parts, plastics, casings and print & packaging material

Inspection Methods

AOI Testing

- Checks for solder paste
- Checks for components down to 0201"
- Checks for missing components, offset, incorrect parts, polarity

X-Ray Inspection

X-Ray provides high-resolution inspection of:

- BGAs
- Bare boards

In-Circuit Testing

In-Circuit Testing is commonly used in conjunction with AOI minimizing functional defects caused by component problems.

- Power-up Test
- Advanced Function Test
- Flash Device Programming
- Functional testing

PART II:

Capacity:

SMT line: 3 millions points per day.

DIP line: 5-10k per day.

PART III

Production line introduction

1. SMT:

SMT workshop has advanced equipment. Each production line is equipped with Automated material loading machine, full automated printing press, High speed SMT machine, multi function machine, reflow and temperature tester. And each line is also equipped with AOI, it not only ensures the capacity but also ensures the SMT assembly quality.

2.PCBA workshop



SMT production line



SMT Automatic material loading machine



Fully Automatic printing press machine



High Speed SMT machine MV2VB



Multi-funtion SMT machine



JT NS800 reflow soldering



AOI



DIP



JT MS350 lead free wave soldering



Programming line



Testing



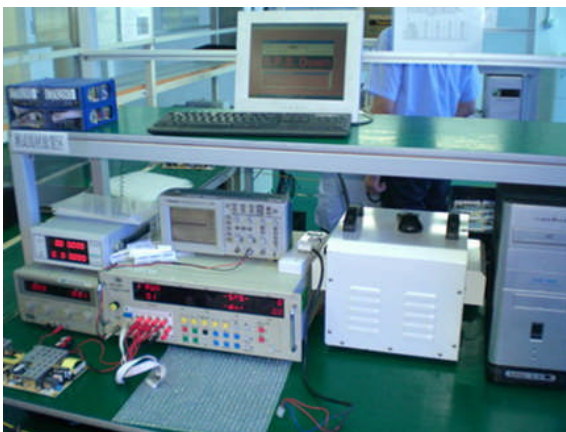
Packing



Central signal source



Testing fixture



SM-268 Power board testing instrument



Aging test room 1



Aging test room 2

IQC Area



QA Area



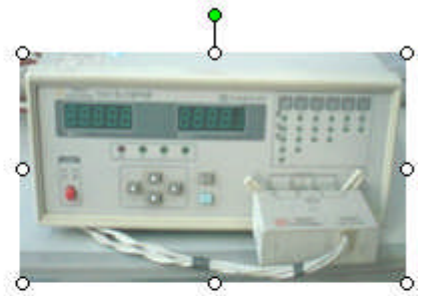
IQC Test Equipment



QT2



Withstanding
Voltage tester



Digital LCR Tester



Solder bath .

QA Test Equipment



Speex Audio Codec



Signal Generator FLUKE 54200



High Temperature Test Chamber

ESD Test Equipment



